



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

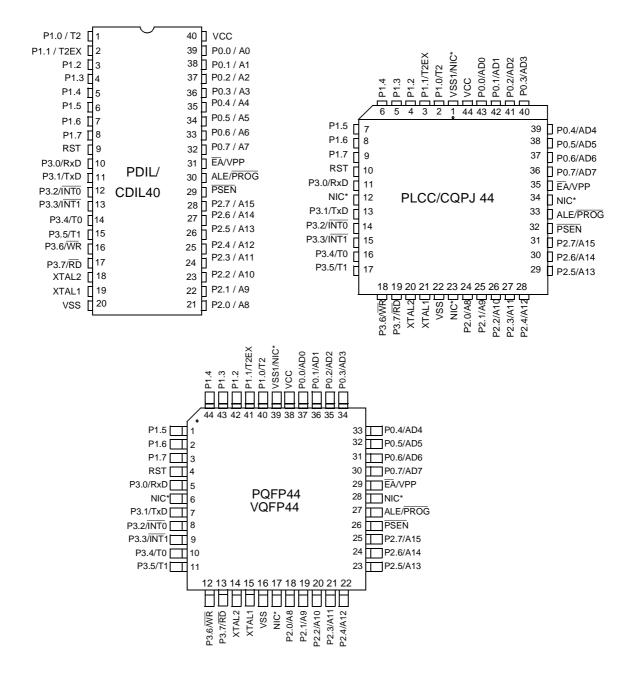
Details

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/20MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMIess
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/at80c32x2-slrum

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Configuration



*NIC: No Internal Connection





Mnemonic	nonic Pin Number			Туре	Name and Function	
	DIL	LCC	VQFP 1.4			
V _{SS}	20	22	16	I	Ground: 0V reference	
Vss1		1	39	I	Optional Ground: Contact the Sales Office for ground connection.	
V _{CC}	40	44	38	I	Power Supply: This is the power supply voltage for normal, idle and power-down operation	
P0.0-P0.7	39- 32	43- 36	37-30	I/O	Port 0 : Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs.Port 0 pins must be polarized to Vcc	
					or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.	
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As	
					inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification.	
					Alternate functions for Port 1 include:	
	1	2	40	I/O	T2 (P1.0): Timer/Counter 2 external count input/Clockout	
	2	3	41	I	T2EX (P1.1): Timer/Counter 2 Reload/Capture/Direction Control	
P2.0-P2.7	21- 28	24- 31	18-25	I/O	Port 2 : Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As	
					inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high- order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX atDPTR). In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX atRi), port 2 emits the contents of the P2 SFR. Some Port 2 pins receive the high order address bits during EPROM programming and verification: P2.0 to P2.4	
P3.0-P3.7	10- 17	11, 13- 19	5, 7-13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulle high by the internal pull-ups and can be used as inputs. A inputs, Port 3 pins that are externally pulled low will source an external pulled low set as a provide the external pulled low set as a prov	
					current because of the internal pull-ups. Port 3 also serves the special features of the 80C51 family, as listed below.	
	10	11	5	I	RXD (P3.0): Serial input port	
	11	13	7	0	TXD (P3.1): Serial output port	
	12	14	8	Ι	INT0 (P3.2): External interrupt 0	

TS8xCx2X2

6



TS80C52X2 Enhanced Features

In comparison to the original 80C52, the TS80C52X2 implements some new features, which are:

- The X2 option
- The Dual Data Pointer
- The 4 level interrupt priority system
- The power-off flag
- The ONCE mode
- The ALE disabling
- Some enhanced features are also located in the UART and the Timer 2

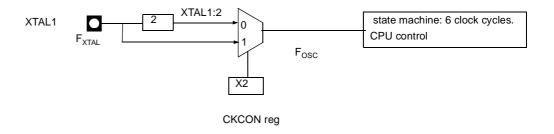
X2 Feature The TS80C52X2 core needs only 6 clock periods per machine cycle. This feature called "X2" provides the following advantages:

- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power
- Save power consumption while keeping same CPU power (oscillator power saving)
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes
- Increase CPU power by 2 while keeping same crystal frequency

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

DescriptionThe clock for the whole circuit and peripheral is first divided by two before being used by
the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1
input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic
ratio between 40 to 60%. Figure 1. shows the clock generation block diagram. X2 bit is
validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD
mode. Figure 2 shows the mode switching waveforms.

Figure 1. Clock Generation Diagram



8



Dual Data Pointer Register (Ddptr)

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called

DPS = AUXR1/bit0 (See Table 5.) that allows the program code to switch between them (Refer to Figure 3).

Figure 3. Use of Dual Pointer

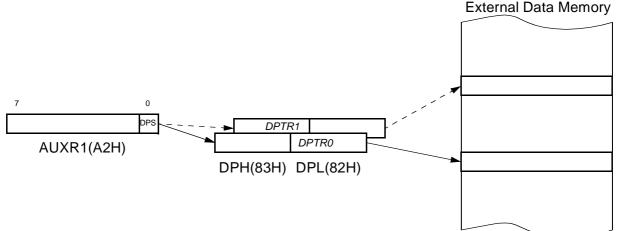


Table 4. AUXR1: Auxiliary Register 1

7	6	5	4	3	2	1	0		
-	-	-	-	GF3	0	-	DPS		
Bit Number	Bit Mnemonic	Description	Description						
7	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.						
6	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.						
5	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.						
4	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.						
3	GF3	This bit is a	general purp	ose user flag					
2	0	Reserved Always stud	Reserved Always stuck at 0						
1	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.						
0	DPS	Clear to sel	Data Pointer Selection Clear to select DPTR0. Set to select DPTR1.						

Reset Value = XXXX XXX0 Not bit addressable

Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

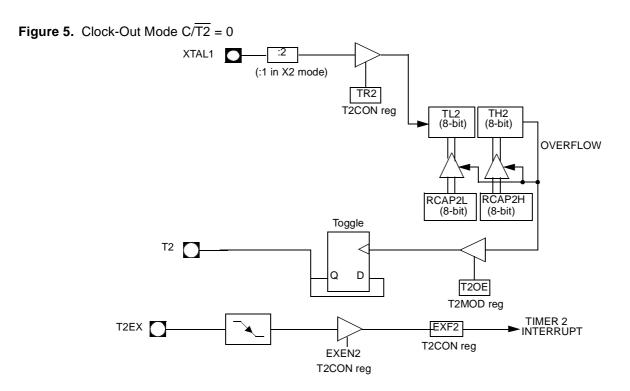
ASSEMBLY LANGUAGE

; Block move using dual data pointers ; Destroys DPTR0, DPTR1, A and PSW ; note: DPS exits opposite of entry state ; unless an extra INC AUXR1 is added 00A2 AUXR1 EQU 0A2H 0000 909000MOV DPTR,#SOURCE ; address of SOURCE 0003 05A2 INC AUXR1 ; switch data pointers 0005 90A000 MOV DPTR,#DEST ; address of DEST 0008 LOOP: 0008 05A2 INC AUXR1 ; switch data pointers 000A E0 MOVX A, atDPTR ; get a byte from SOURCE 000B A3 INC DPTR ; increment SOURCE address 000C 05A2 INC AUXR1 ; switch data pointers 000E F0 MOVX atDPTR, A ; write the byte to DEST 000F A3 INC DPTR ; increment DEST address 0010 70F6JNZ LOOP ; check for 0 terminator 0012 05A2 INC AUXR1 ; (optional) restore DPS

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.



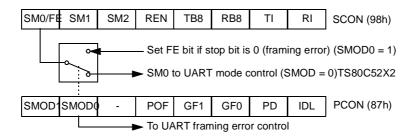




14 **TS8xCx2X2**

TS80C52X2 Serial I/O
PortThe serial I/O port in the TS80C52X2 is compatible with the serial I/O port in the 80C52.
It provides both synchronous and asynchronous communication modes. It operates as
an Universal Asynchronous Receiver and Transmitter (UART) in three full-duplex
modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simul-
taneously and at different baud rates
Serial I/O port includes the following enhancements:
 Framing Error DetectionFraming bit error detection is provided for the three asynchronous modes (modes 1, 2
and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON regis-
ter (See Figure 6).

Figure 6. Framing Error Block Diagram



When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See Table 9.) bit is set.

Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 7. and Figure 8.).

Figure 7. UART Timings in Mode 1

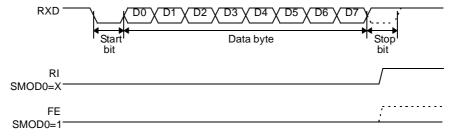




Table 10. PCON RegisterPCON - Power Control Register (87h)

7	6	5	4	3	2	1	0			
SMOD1	SMOD0	-	POF	GF1	GF0	PD	IDL			
Bit Number	Bit Mnemonic	Descriptio	Description							
7	SMOD1		t Mode bit 1 act double bau	ud rate in mode	e 1, 2 or 3.					
6	SMOD0	Clear to se	Serial port Mode bit 0 Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.							
5	-	Reserved The value	Reserved The value read from this bit is indeterminate. Do not set this bit.							
4	POF	Clear to ree Set by hard	Power-off Flag Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.							
3	GF1	Cleared by		eral purpose us purpose usage						
2	GF0	Cleared by	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.							
1	PD	Cleared by	Power-down mode bit Cleared by hardware when reset occurs. Set to enter power-down mode.							
0	IDL	Idle mode bit Clear by hardware when interrupt or reset occurs. Set to enter idle mode.								

Reset Value = 00X1 0000b Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.



Table 14.IPH RegisterIPH - Interrupt Priority High Register (B7h)

7	6	5	4	3	2	1	0
-	-	PT2H	PSH	PT1H	PX1H	РТОН	РХОН
Bit Number	Bit Mnemonic	Description					
7	-	Reserved The value rea	d from this bit	is indetermina	ate. Do not se	t this bit.	
6	-	Reserved The value rea	d from this bit	is indetermina	ate. Do not se	t this bit.	
5	PT2H	Timer 2 over PT2H PT2 0 0 1 0 1 1	f low interrup <u>Priority Leve</u> Lowest Highest	t Priority High 한	n bit		
4	PSH	Serial port P PSH PS 0 0 0 1 1 0 1 1	riority High b <u>Priority Leve</u> Lowest Highest				
3	PT1H	Timer 1 over PT1H PT1 0 0 0 1 1 0 1 1		t Priority High 키	n bit		
2	PX1H	External inte PX1H PX1 0 0 1 0 1 1 1 1	rrupt 1 Priori Priority Leve Lowest Highest				
1	РТОН	Timer 0 over PT0H PT0 0 0 1 0 1 1		t Priority High 한	n bit		
0	РХОН	External inte PX0H PX0 0 0 1 1 1 1	rrupt 0 Priori <u>Priority Leve</u> Lowest Highest	ty High bit <u>키</u>			

Reset Value = XX00 0000b Not bit addressable





ONCE[™] Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS80C52X2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C52X2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and PSEN is high.
- Hold ALE low as RST is deactivated.

While the TS80C52X2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 26. shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

Table 16. External Pin Status during ONCE Mode

ALE	PSEN	Port 0	Port 1	Port 2	Port 3	XTAL1/2
Weak pull- up	Weak pull- up	Float	Weak pull- up	Weak pull- up	Weak pull- up	Active

12,000 μ W/cm² rating for 30 minutes, at a distance of about 25 mm, should be sufficient. An exposure of 1 hour is recommended with most of standard erasers.

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelength shorter than approximately 4,000 Å. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room-level fluorescent lighting) could cause inadvertent erasure. If an application subjects the device to this type of exposure, it is suggested that an opaque label be placed over the window.

Signature Bytes The TS80/87C52X2 has four signature bytes in location 30h, 31h, 60h and 61h. To read these bytes follow the procedure for EPROM verify but activate the control lines provided in Table 31. for Read Signature Bytes. Table 35. shows the content of the signature byte for the TS80/87C52X2.

Location	Contents	Comment
30h	58h	Manufacturer Code: Atmel
31h	57h	Family Code: C51 X2
60h	2Dh	Product name: TS80C52X2
60h	ADh	Product name:TS87C52X2
60h	20h	Product name: TS80C32X2
61h	FFh	Product revision number

Table 21. Signature Bytes Content





Electrical Characteristics

Absolute Maximum Ratings⁽¹⁾

Ambiant Temperature Under Bias:	
C = commercial	0°C to 70°C
I = industrial	40°C to 85°C
Storage Temperature	65°C to + 150°C
Voltage on V _{CC} to V _{SS}	0.5V to + 7 V
Voltage on V _{PP} to V _{SS}	0.5V to + 13 V
Voltage on Any Pin to V _{SS}	0.5V to V _{CC} + 0.5V
Power Dissipation	1 W ⁽²⁾

- Notes: 1. Stresses at or above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
 - 2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

Power Consumption Measurement Since the introduction of the first C51 devices, every manufacturer made operating lcc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating lcc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

DC Parameters for	TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.
Standard Voltage	TA = -40°C to +85°C; $V_{SS} = 0$ V; $V_{CC} = 5V \pm 10\%$; F = 0 to 40 MHz.

Table 22.	DC Parameters	in	Standard	Voltage
-----------	---------------	----	----------	---------

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3 ⁽⁶⁾			0.3 0.45 1.0	V V V	$I_{OL} = 100 \ \mu A^{(4)}$ $I_{OL} = 1.6 \ m A^{(4)}$ $I_{OL} = 3.5 \ m A^{(4)}$
V _{OL1}	Output Low Voltage, port 0 ⁽⁶⁾			0.3 0.45 1.0	V V V	$I_{OL} = 200 \ \mu A^{(4)}$ $I_{OL} = 3.2 \ m A^{(4)}$ $I_{OL} = 7.0 \ m A^{(4)}$
V _{OL2}	Output Low Voltage, ALE, PSEN			0.3 0.45 1.0	V V V	$I_{OL} = 100 \ \mu A^{(4)}$ $I_{OL} = 1.6 \ m A^{(4)}$ $I_{OL} = 3.5 \ m A^{(4)}$



Table 23. DC Parameters for Low Voltage

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3 (6)			0.45	V	I _{OL} = 0.8 mA ⁽⁴⁾
V _{OL1}	Output Low Voltage, port 0, ALE, PSEN (6)			0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
V _{OH}	Output High Voltage, ports 1, 2, 3	0.9 V _{CC}			V	I _{OH} = -10 μA
V _{OH1}	Output High Voltage, port 0, ALE, PSEN	0.9 V _{CC}			V	I _{OH} = -40 μA
I _{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	μA	Vin = 0.45V
ILI	Input Leakage Current			±10	μA	$0.45V < Vin < V_{CC}$
I _{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	μA	Vin = 2.0 V
R _{RST}	RST Pulldown Resistor	50	90 ⁽⁵⁾	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T _A = 25°C
I _{PD}	Power Down Current		20 ⁽⁵⁾ 10 ⁽⁵⁾	50 30	μA	$V_{CC} = 2.0 \text{ V to } 5.5 \text{V}^{(3)}$ $V_{CC} = 2.0 \text{ V to } 3.3 \text{ V}^{(3)}$
I _{cc} under RESET	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			1 + 0.2 Freq (MHz) at12MHz 3.4 at16MHz 4.2	mA	$V_{CC} = 3.3 V^{(1)}$
I _{CC} operating	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			1 + 0.3 Freq (MHz) at12MHz 4.6 at16MHz 5.8	mA	V _{CC} = 3.3 V ⁽⁸⁾
I _{CC} idle	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			0.15 Freq (MHz) + 0.2 at12MHz 2 at16MHz 2.6	mA	V _{CC} = 3.3 V ⁽²⁾

Notes: 1. I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 17.), V_{IL} = V_{SS} + 0.5V,

 $V_{IH} = V_{CC} - 0.5V$; XTAL2 N.C.; $\overline{EA} = RST = Port 0 = V_{CC}$. I_{CC} would be slightly higher if a crystal oscillator used..

2. Idle I_{CC} is measured with all out<u>put</u> pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5$ ns, $V_{IL} = V_{SS} + 0.5V$, $V_{IH} = V_{CC} - 0.5V$; XTAL2 N.C; Port 0 = V_{CC} ; EA = RST = V_{SS} (see Figure 15.).

Power Down I_{CC} is measured with all output pins disconnected; EA = V_{SS}, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 16.).

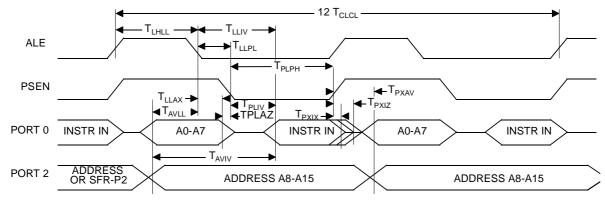
4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.

5. Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.

 Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows: Maximum I_{OL} per port pin: 10 mA Maximum I_{OL} per 8-bit port:

External Program Memory Read Cycle

Figure 18. External Program Memory Read Cycle



External Data Memory Characteristics

 Table 29.
 Symbol Description

Symbol	Parameter
T _{RLRH}	RD Pulse Width
T _{WLWH}	WR Pulse Width
T _{RLDV}	RD to Valid Data In
T _{RHDX}	Data Hold After RD
T _{RHDZ}	Data Float After RD
T _{LLDV}	ALE to Valid Data In
T _{AVDV}	Address to Valid Data In
T _{LLWL}	ALE to WR or RD
T _{AVWL}	Address to WR or RD
T _{QVWX}	Data Valid to WR Transition
T _{QVWH}	Data set-up to WR High
T _{WHQX}	Data Hold After WR
T _{RLAZ}	RD Low to Address Float
T _{WHLH}	RD or WR High to ALE high





Table 30.	AC Parameters for a Fix Clock
-----------	-------------------------------

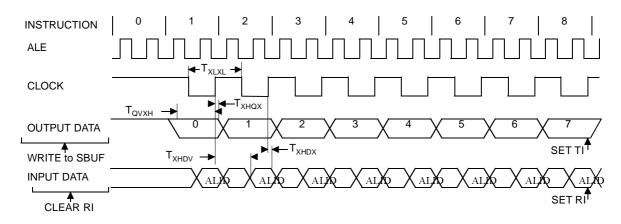
Speed	-I 40 I		X2 n 30 l 60 l	V node MHz MHz uiv.	stan mod	V dard le 40 Hz	X2 n 20 l 40 l	L node MHz MHz uiv.	stan mo	L dard ode MHz	Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T _{RLRH}	130		85		135		125		175		ns
T _{WLWH}	130		85		135		125		175		ns
T _{RLDV}		100		60		102		95		137	ns
T _{RHDX}	0		0		0		0		0		ns
T _{RHDZ}		30		18		35		25		42	ns
T _{LLDV}		160		98		165		155		222	ns
T _{AVDV}		165		100		175		160		235	ns
T _{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T _{AVWL}	75		47		80		70		103		ns
T _{QVWX}	10		7		15		5		13		ns
T _{QVWH}	160		107		165		155		213		ns
T _{WHQX}	15		9		17		10		18		ns
T _{RLAZ}		0		0		0		0		0	ns
T _{WHLH}	10	40	7	27	15	35	5	45	13	53	ns

Symbol	Туре	Standard Clock	X2 Clock	-М	-V	-L	Units
T _{XLXL}	Min	12 T	6 T				ns
T _{QVHX}	Min	10 T - x	5 T - x	50	50	50	ns
T _{XHQX}	Min	2 T - x	T - x	20	20	20	ns
T _{XHDX}	Min	х	х	0	0	0	ns
T _{XHDV}	Max	10 T - x	5 T- x	133	133	133	ns

Table 34. AC Parameters for a Variable Clock: Derating Formula

Shift Register Timing Waveforms







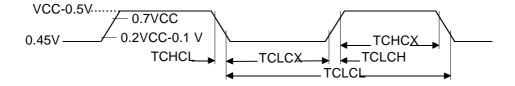
External Clock Drive Characteristics (XTAL1)

Table 36. AC Parameters

Symbol	Parameter	Min	Max	Units
T _{CLCL}	Oscillator Period	25		ns
T _{CHCX}	High Time	5		ns
T _{CLCX}	Low Time	5		ns
T _{CLCH}	Rise Time		5	ns
T _{CHCL}	Fall Time		5	ns
T _{CHCX} /T _{CLCX}	Cyclic ratio in X2 mode	40	60	%

External Clock Drive Waveforms

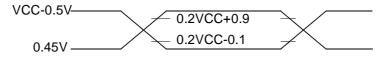
Figure 23. External Clock Drive Waveforms



AC Testing Input/Output Waveforms

Figure 24. AC Testing Input/Output Waveforms

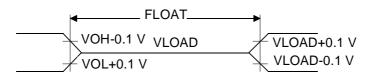
INPUT/OUTPUT



AC inputs during testing are driven at V_{CC} - 0.5 for a logic "1" and 0.45V for a logic "0". Timing measurement are made at V_{IH} min for a logic "1" and V_{IL} max for a logic "0".

Float Waveforms

Figure 25. Float Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OL}/I_{OH} \ge \pm 20$ mA.





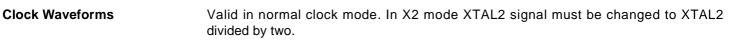
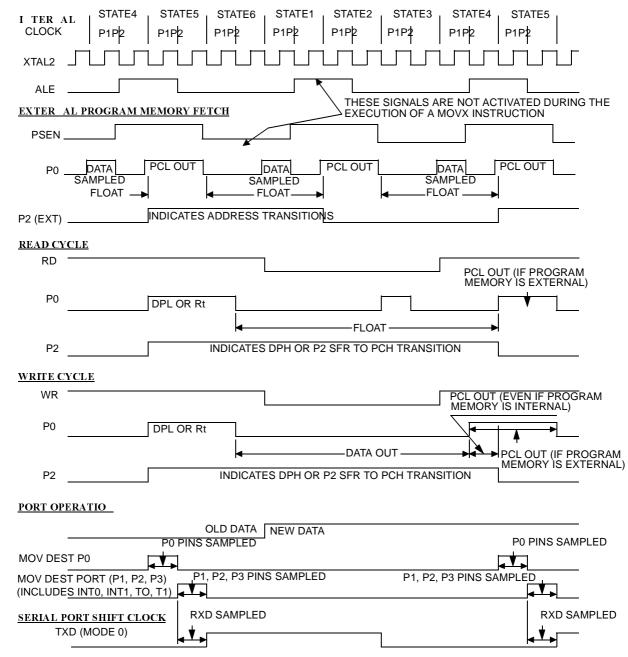


Figure 26. Clock Waveforms



This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though ($T_A = 25^{\circ}C$ fully loaded) RD and WR propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.

Ordering Information

Table 37. Possible Ordering Entries

Part Number ⁽³⁾	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS80C32X2-MCA	ROMLess	5V <u>±</u> 10%	Commercial	40 MHz ⁽¹⁾	PDIL40	Stick
TS80C32X2-MCB	ROMLess	5V <u>±</u> 10%	Commercial	40 MHz ⁽¹⁾	PLCC44	Stick
TS80C32X2-MCC	ROMLess	5V <u>±</u> 10%	Commercial	40 MHz ⁽¹⁾	PQFP44	Tray
TS80C32X2-MCE	ROMLess	5V <u>±</u> 10%	Commercial	40 MHz ⁽¹⁾	VQFP44	Tray
TS80C32X2-LCA	ROMLess	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PDIL40	Stick
TS80C32X2-LCB	ROMLess	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PLCC44	Stick
TS80C32X2-LCC	ROMLess	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PQFP44	Tray
TS80C32X2-LCE	ROMLess	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	VQFP44	Tray
TS80C32X2-VCA	ROMLess	5V <u>±</u> 10%	Commercial	60 MHz ⁽³⁾	PDIL40	Stick
TS80C32X2-VCB	ROMLess	5V <u>±</u> 10%	Commercial	60 MHz ⁽³⁾	PLCC44	Stick
TS80C32X2-VCC	ROMLess	5V <u>±</u> 10%	Commercial	60 MHz ⁽³⁾	PQFP44	Tray
TS80C32X2-VCE	ROMLess	5V <u>±</u> 10%	Commercial	60 MHz ⁽³⁾	VQFP44	Tray
TS80C32X2-MIA	ROMLess	5V <u>±</u> 10%	Industrial	40 MHz ⁽¹⁾	PDIL40	Stick
TS80C32X2-MIB	ROMLess	5V <u>±</u> 10%	Industrial	40 MHz ⁽¹⁾	PLCC44	Stick
TS80C32X2-MIC	ROMLess	5V <u>±</u> 10%	Industrial	40 MHz ⁽¹⁾	PQFP44	Tray
TS80C32X2-MIE	ROMLess	5V <u>±</u> 10%	Industrial	40 MHz ⁽¹⁾	VQFP44	Tray
TS80C32X2-LIA	ROMLess	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PDIL40	Stick
TS80C32X2-LIB	ROMLess	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PLCC44	Stick
TS80C32X2-LIC	ROMLess	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PQFP44	Tray
TS80C32X2-LIE	ROMLess	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	VQFP44	Tray
TS80C32X2-VIA	ROMLess	5V <u>±</u> 10%	Industrial	60 MHz ⁽³⁾	PDIL40	Stick
TS80C32X2-VIB	ROMLess	5V <u>±</u> 10%	Industrial	60 MHz ⁽³⁾	PLCC44	Stick
TS80C32X2-VIC	ROMLess	5V <u>±</u> 10%	Industrial	60 MHz ⁽³⁾	PQFP44	Tray
TS80C32X2-VIE	ROMLess	5V <u>±</u> 10%	Industrial	60 MHz ⁽³⁾	VQFP44	Tray
AT80C32X2-3CSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz ⁽¹⁾	PDIL40	Stick
AT80C32X2-SLSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz ⁽¹⁾	PLCC44	Stick
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz ⁽¹⁾	VQFP44	Tray
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz ⁽¹⁾	VQFP44	Tape & Reel
AT80C32X2-3CSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	PDIL40	Stick
AT80C32X2-SLSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	PLCC44	Stick



Table 37. Possible Ordering Entries (Continued)

Part Number ⁽³⁾	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
AT80C52X2zzz-3CSUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	PDIL40	Stick
AT80C52X2zzz-SLSUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	PLCC44	Stick
AT80C52X2zzz-RLTUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	VQFP44	Tray
AT80C52X2zzz-3CSUV	8K ROM	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	PDIL40	Stick
AT80C52X2zzz-SLSUV	8K ROM	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	PLCC44	Stick
AT80C52X2zzz-RLTUV	8K ROM	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	VQFP44	Tray
TODZOCOVO MOA		E) (- 4.00/	O a manazial	40 MUL-(1)		Otiale
TS87C52X2-MCA	8K OTP	5V ±10%	Commercial	40 MHz ⁽¹⁾	PDIL40	Stick
TS87C52X2-MCB	8K OTP	5V ±10%	Commercial	40 MHz ⁽¹⁾	PLCC44	Stick
TS87C52X2-MCC	8K OTP	5V ±10%	Commercial	40 MHz ⁽¹⁾	PQFP44	Tray
TS87C52X2 -MCE	8K OTP	5V ±10%	Commercial	40 MHz ⁽¹⁾	VQFP44	Tray
TS87C52X2 -LCA	8K OTP	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PDIL40	Stick
TS87C52X2-LCB	8K OTP	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PLC44	Stick
TS87C52X2-LCC	8K OTP	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PQFP44	Tray
TS87C52X2-LCE	8K OTP	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	VQFP44	Tray
TS87C52X2-VCA	8K OTP	5V ±10%	Commercial	60 MHz ⁽³⁾	PDIL40	Stick
TS87C52X2 -VCB	8K OTP	5V ±10%	Commercial	60 MHz ⁽³⁾	PLCC44	Stick
TS87C52X2-VCC	8K OTP	5V ±10%	Commercial	60 MHz ⁽³⁾	PQFP44	Tray
TS87C52X2-VCE	8K OTP	5V ±10%	Commercial	60 MHz ⁽³⁾	VQFP44	Tray
TS87C52X2-MIA	8K OTP	5V ±10%	Industrial	40 MHz ⁽¹⁾	PDIL40	Stick
TS87C52X2-MIB	8K OTP	5V ±10%	Industrial	40 MHz ⁽¹⁾	PLCC44	Stick
TS87C52X2-MIC	8K OTP	5V ±10%	Industrial	40 MHz ⁽¹⁾	PQFP44	Tray
TS87C52X2-MIE	8K OTP	5V ±10%	Industrial	40 MHz ⁽¹⁾	VQFP44	Tray
TS87C52X2-LIA	8K OTP	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PDIL40	Stick
TS87C52X2-LIB	8K OTP	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PLCC44	Stick
TS87C52X2-LIC	8K OTP	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PQFP44	Tray
TS87C52X2-LIE	8K OTP	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	VQFP44	Tray
TS87C52X2-VIA	8K OTP	5V ±10%	Industrial	60 MHz ⁽³⁾	PDIL40	Stick
TS87C52X2 -VIB	8K OTP	5V ±10%	Industrial	60 MHz ⁽³⁾	PLCC44	Stick
TS87C52X2-VIC	8K OTP	5V ±10%	Industrial	60 MHz ⁽³⁾	PQFP44	Tray
TS87C52X2-VIE	8K OTP	5V ±10%	Industrial	60 MHz ⁽³⁾	VQFP44	Tray

